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Trademarks:  
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To The Honorable  
Please record the

1. Name of conveying party(ies):

Sumio MORIOKA  
Akashi SATOH  
Gang ZHANG

Additional name(s) of conveying party(ies) attached? \_\_\_Yes XNo

2. Name and address of receiving party(ies):

Name: International Business Machines Corporation  
Address: New Orchard Road  
Armonk, NY 10504

Additional name(s) & addresses attached? \_\_\_ Yes X No

3. Nature of conveyance:

X Assignment

Execution Date(s): May 7, 2003 and May 30, 2003.

4. Patent Application number(s)

10/349,519

Execution Date(s): May 7, 2003 and May 30, 2003.

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Louis P. Herzberg  
Address: IBM Corporation  
Intellectual Property Law  
P.O. Box 218  
Yorktown Heights, NY 10598

6. Total number of applications involved: 1

7. Total fee (37 CFR 3.41): \$40.00

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Louis P. Herzberg (Reg. 41,500)  
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*Louis Herzberg*  
Signature

June 16, 03  
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06/23/2003 TD1071 00000101 090468 10349519

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# Assignment

Whereas, we

Inventor  
and City

(1) Sumio Morioka

of Kanagawa-ken  
and Country of Japan

(2) Akashi Satoh

of Kanagawa-ken  
and Country of Japan

(3)Gang Zhang

of Kanagawa-ken  
and Country of Japan

have invented certain improvements in

TITLE COMBINATIONAL CIRCUIT, ENCRYPTION CIRCUIT, METHOD FOR CONSTRUCTING  
THE SAME AND PROGRAM

and executed, respectively, a United States patent application therefor on

DATES THAT (1) *May 7, 2003*, and (2) *May 7, 2003*. (3) *May 30, 2003*

INVENTORS  
SIGNED THE  
DECLARATION

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM) desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

CITY (1) at *Yamato*  
DATE on *May 7, 2003*,  
Signed

*Sumio Morioka* SIGNATURE  
( Sumio Morioka ) INVENTOR  
FIRST NAME MIDDLE INITIAL LAST NAME

CITY and (2) at *Yamato*  
DATE on *May 7, 2003*,  
Signed

*Akashi Satoh* SIGNATURE  
( Akashi Satoh ) INVENTOR  
FIRST NAME MIDDLE INITIAL LAST NAME

CITY and (3) at *Yamato*  
DATE on *May 30, 2003*,  
Signed

*Gang Zhang* SIGNATURE  
( Gang Zhang ) INVENTOR  
FIRST NAME MIDDLE INITIAL LAST NAME